

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
4 April 2002 (04.04.2002)

PCT

(10) International Publication Number
WO 02/26443 A1

(51) International Patent Classification⁷: **B24B 37/04**,
41/06 // H01L 21/304

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(21) International Application Number: PCT/EP01/10186

(22) International Filing Date:
4 September 2001 (04.09.2001)

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(25) Filing Language: English

(81) Designated States (*national*): JP, KR, SG, US.

(26) Publication Language: English

(84) Designated States (*regional*): European patent (AT, BE,
CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC,
NL, PT, SE, TR).

(30) Priority Data:
00121485.7 29 September 2000 (29.09.2000) EP

Published:

- with international search report
- before the expiration of the time limit for amending the
claims and to be republished in the event of receipt of
amendments

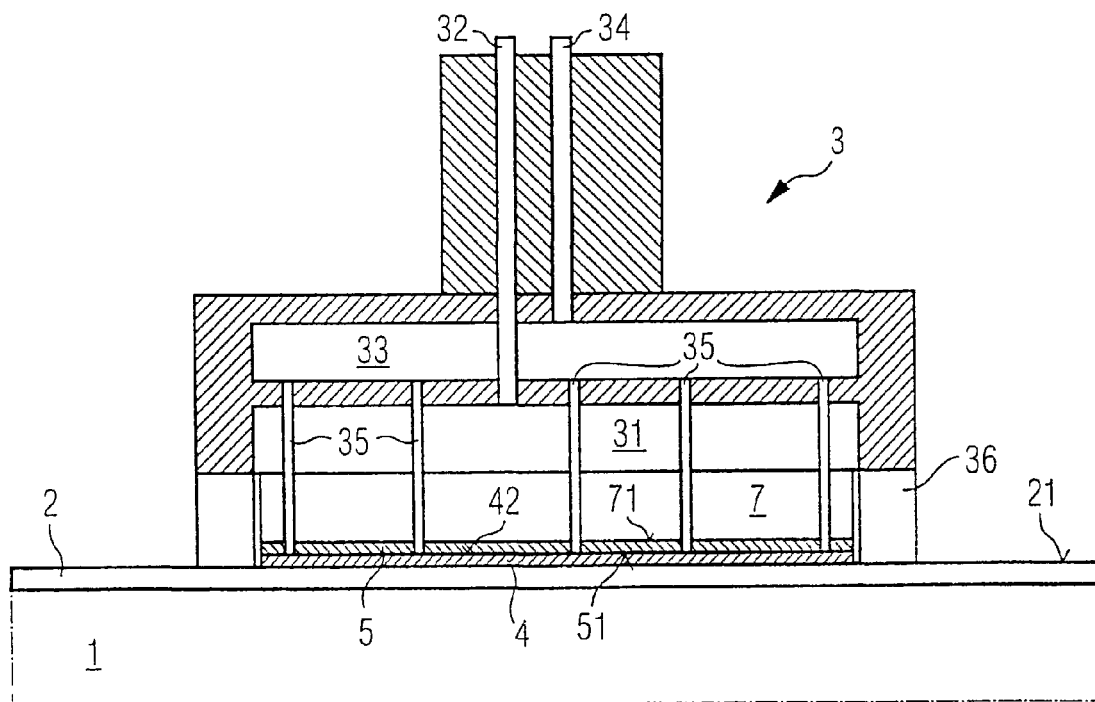
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*For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.*

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(54) Title: ARRANGEMENT FOR POLISHING DISK-LIKE OBJECTS



(57) Abstract: A polish head (3) for Chemical Mechanical Polishing comprises a backing film (5) made of silicone on a rigid support element (6, 7), preferably consisting of amorphous ceramic. The silicone backing film (5) is fabricated by molding, thereby enabling an appropriate cross-sectional shape for specific polishing needs. The invention provides a uniform polishing of a semiconductor wafer (4).